

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	
)	Examiner: Not yet assigned
Scot A. Kellar et al.)	
)	Art Unit: Not yet assigned
Serial No.: Not yet assigned)	
)	
Filed: Herewith)	
)	
For: WAFER BONDING FOR)	
THREE-DIMENSIONAL (3D))	
<u>INTEGRATION</u>)	
Which is a Divisional of Application of:)	
)	
Serial No: 10/066,643)	
)	
<u>Filed: February 6, 2002</u>)	

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Applicant hereby requests consideration of the enclosed Information Disclosure Statement pursuant to 37 C.F.R §1.97(b). Attached is the PTO Form 1449 from the parent application filed on February 6, 2002 (Serial No. 10/066,643). These previous application is relied upon for an earlier filing date under 35 U.S.C. §120.

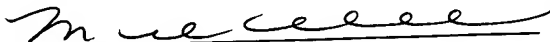
Pursuant to C.F.R. §1.98(d), copies of the references are not being provided herewith since they were previously sent to the Patent and Trademark Office. Please consider these cited documents in the currently pending §1.53(b) divisional application filed on February 6, 2002.

Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 10/27, 2003


Michael A. Bernadicou
Reg. No. 34,935

12400 Wilshire Blvd.
Seventh Floor
Los Angeles, CA 90025-1026
(408) 720-8300

Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 219.40605X00	SERIAL NO. 10/066,643
	APPLICANT Scot A. KELLAR et al.	
	FILING DATE February 6, 2002	GROUP 2811

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
	AA					
	AB					
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					
	AK					
	AL					

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AM						
	AN						
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AU	"Ultra Thin Electronics for Space Applications", 2001 Electronic Components and Technology Conference, 2001 IEEE
	AV	"Copper Wafer Bonding"; A. Fan, A. Rahman, and R. Reif; Electrochemical and Solid-State Letters, 2 (10) 534-536 (1999)
	AW	"Face to Face Wafer Bonding for 3D Chip Stack Fabrication to Shorten Wire Lengths", June 27-29, 2000 VMIC Conference 2000 IMIC - 200/00/0090(c)
	AX	"InterChip Via Technology for Vertical System Integration", Fraunhofer Institute for Reliability and Microintegration, Munich, Germany; Infineon Technologies AG, Munich, Germany; 2001 IEEE
	AY	
	AZ	
Examiner		Date Considered